

1. Record Nr.	UNINA9911104981603321
Titolo	Electrodeposition : properties, processes, and applications // Udit Surya Mohanty, editor
Pubbl/distr/stampa	New York, : Nova Science Publishers, c2012
ISBN	1-61470-845-2
Edizione	[1st ed.]
Descrizione fisica	1 online resource (375 p.)
Collana	Electrical Engineering Developments
Altri autori (Persone)	MohantyUdit Surya
Disciplina	671.732
Soggetti	Alloy plating Electroplating
Lingua di pubblicazione	Inglese
Formato	Materiale a stampa
Livello bibliografico	Monografia
Note generali	Description based upon print version of record.
Nota di bibliografia	Includes bibliographical references at the end of each chapters and index.
Nota di contenuto	""ELECTRODEPOSITION ""; ""ELECTRODEPOSITION ""; ""CONTENTS ""; ""PREFACE ""; ""A REVIEW ON THE ELECTRODEPOSITION OF NICKEL: SYNTHESIS, MAGNETIC, THERMODYNAMIC PROPERTIES AND ITS POTENTIAL APPLICATIONS ""; ""ABSTRACT ""; ""INTRODUCTION ""; ""1.1. CRYSTAL STRUCTURES OF NICKEL ""; ""1.2. SYNTHESIS ""; ""1.2.1. FCC Nickel ""; ""1.2.2. HCP Nickel""; ""1.3. MAGNETIC AND THERMODYNAMIC PROPERTIES ""; ""1.4. APPLICATIONS ""; ""CONCLUSION ""; ""REFERENCES""; ""DEPOSITION AND PROPERTIES OF ELECTROCHEMICAL COMPOSITE COATINGS ""; ""ABSTRACT ""; ""INTRODUCTION "" ""2.1. DIFFERENT TYPES OF ELECTROCHEMICAL COMPOSITE COATINGS (ECC) """"2.1.1. Nickel-Based ECC ""; ""2.1.2. Chromium-Based ECC ""; ""2.1.3. Copper-Based ECC ""; ""2.1.4. Iron-Based ECC""; ""2.1.5. Zinc-Based ECC ""; ""2.1.6. ECC Based on Noble Metals ""; ""CONCLUSION ""; ""REFERENCES ""; ""ELECTRODEPOSITION OF AU-SN ALLOYS ""; ""ABSTRACT""; ""INTRODUCTION ""; ""3.1. ELECTRODEPOSITION OF AU-SN ALLOYS FROM A SINGLE SOLUTION""; ""3.1.1. Solution Preparation ""; ""3.2. SOLUTION STABILITY ""; ""3.2.1. Solution Precipitation and Turbidity Measurements "" ""3.2.2. Characterization of Precipitates """"3.2.3. UV/Vis Spectroscopy and X-Ray Photoelectron Spectroscopy Studies ""; ""3.3. MICROSTRUCTURE OF ELECTRODEPOSITED FILMS""; ""3.3.1. Microstructure of Eutectic Deposits and Reflowed Solder ""; ""3.4.

RECOVERY OF AU FROM THE WASTE SOLUTION ""; ""3.5. SEQUENTIAL ELECTRODEPOSITION FROM TWO SEPARATE SOLUTIONS ""; ""3.5.1. Solution Preparation and Electrodeposition of Pure Au Films ""; ""3.5.2. Solution Preparation and Electrodeposition of Pure Sn Films ""; ""3.5.3. Microstructure of Sequentially Deposited Eutectic Alloys and Reflowed Solder""

""CONCLUSION """"ACKNOWLEDGMENTS ""; ""REFERENCES ""; ""ELECTROCHEMICAL CORROSION BEHAVIOUR OF LEAD a€? FREE SOLDER ALLOYS IN 3.5 % NaCl SOLUTION""; ""ABSTRACT ""; ""INTRODUCTION ""; ""4.1. ELECTROCHEMICAL CORROSION STUDY OF SN-XAG-0.5 CU SOLDER ALLOYS ""; ""4. 1.1. Polarisation Study ""; ""4.1.2. Surface Characterisation Studies ""; ""4.2. ELECTROCHEMICAL CORROSION STUDY OF SN-8.5ZN-XAG-0.1AL-0.05GA SOLDER ALLOYS ""; ""4.2.1. Polarization Study ""; ""4.2.2. Surface Characterisation Studies""; ""4.3. ELECTROCHEMICAL CORROSION STUDY OF SN-8.5ZN-X AL-0.5 GA SOLDER ALLOYS ""

""4.3.1. Polarisation Study""""4.3.2. Surface Characterisation Studies: ""; ""CONCLUSION""; ""REFERENCES ""; ""PROPERTIES AND APPLICATIONS OF NICKEL COATINGS SYNTHESIZED BY PULSE ELECTRODEPOSITION""; ""ABSTRACT""; ""INTRODUCTION ""; ""5.1. THE SYNTHESIS OF NICKEL COATING WITH HIGH DENSITY NT ""; ""5.1.1. The Synthesis of Nickel Coatings with High Density NT ""; ""5.1.2. The Corrosion Property of Nickel Coating with High Density NT ""; ""5.1.3. The Semiconducting Behavior of Passive Film of NT Nickel ""; ""5.2. INHIBITION OF HYDROGEN BLISTER ON Cu a€? SN ALLOY COATINGS ""

""5.2.1. Influence of Current Density on Hydrogen Permeation ""

Sommario/riassunto

Covers such topics as electrochemical synthesis of non-stoichiometric hydroxyapatite-nanodiamond composite coating; electrodeposited biomimetic hydroxyapatite functionalized by lactoferrin for its potential use as bone-implantable biomaterials; and, preparation of CuInSe₂ thin films and its potential application in photovoltaic devices.